

Title (en)
METHOD FOR ASSEMBLING A CHIP IN A FLEXIBLE SUBSTRATE

Title (de)
VERFAHREN ZUR CHIPMONTAGE BEI EINEM FLEXIBLEN SUBSTRAT

Title (fr)
PROCÉDÉ D'ASSEMBLAGE D'UNE PUCE DANS UN SUBSTRAT SOUPLE

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Abstract (en)
[origin: WO2012007655A1] According to the invention, a substrate, provided with an electrically conductive wire (3) coated with an electrically insulating material, is impregnated with a polymerisable material (4). A reception area (5) for a chip (2) is formed on a surface of the substrate (1) by means of deformation. The reception area (5) is stiffened using the polymerisable material (4). The chip (2) is disposed in the reception area (5) and an electrical connection area (8) of the chip (2) is connected electrically to the electrically conductive wire of the substrate (1).

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